

# PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Jong Min LEE	10/06/2010
<b>RECEIVING PARTY DATA</b>	
Name:	SHELKO Electronics Co. Ltd.
Street Address:	713 Suseo-dong, Gangnam-gu
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City:	Seoul
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Postal Code:	135-539
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	29337102
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Total Attachments: 2 source=jd20181_assign#page1.tif source=jd20181_assign#page2.tif	

CH \$40.00 29337102

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**PATENT**  
**REEL: 025149 FRAME: 0092**

**ASSIGNMENT OF PATENT APPLICATION**

WHEREAS, I/We, LEE, Jong Mi, a citizen of Republic of Korea, residing at 24-17, Seodun-dong, Gwonseon-gu, Suwon Si, Gyeonggi-Do 441-100 Republic of Korea, PARK, Ju Gun, a citizen of Republic of Korea, residing at 3-402, Hanyang Apt. Apgujeong-dong, Gangnam-gu, Seoul 135-794 Republic of Korea, OH, Jong Min, a citizen of Republic of Korea, residing at 24-17, 611-1802, Tapmaeul Byoksan Apt. 517 Yatap-dong, Bundang-gu, Seongnam Si, Gyeonggi-Do 463-927 Republic of Korea, OH, Jong Hyok, a citizen of Republic of Korea, residing at 611-1802, Tapmaeul Byoksan Apt. 517 Yatap-dong, Bundang-gu, Seongnam Si, Gyeonggi-Do 463-927 Republic of Korea and ASSIGNOR(S), am/are the inventor(s) of an invention in (insert title)

**A PORTABLE TERMINAL WITH AN IMAGE DESIGN**

for which I/we have executed an application for Letters Patent of the United States,

(Check One) ☒ on \_\_\_\_\_ ;  
☐ U.S. Serial Number \_\_\_\_\_ filed on \_\_\_\_\_;  
☐ International Application No. \_\_\_\_\_ filed on \_\_\_\_\_

**PRIOR FOREIGN APPLICATION(S)****Priority Claimed**

<u>30-2010-0017483</u> (Number)	<u>Rep. of Korea</u> (Country)	<u>20 April 2010</u> (Day/Month/Year Filed)	Yes: <input checked="" type="checkbox"/> No: <input type="checkbox"/>
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	Yes: <input type="checkbox"/> No: <input type="checkbox"/>

**DOMESTIC BENEFIT/NATIONAL STAGE APPLICATION(S)**

_____ (Prior Application Status)	_____ (Continuity Type)	_____ (Prior Application Number)	_____ (Filing Date)
_____ (Prior Application Status)	_____ (Continuity Type)	_____ (Prior Application Number)	_____ (Filing Date)

and  
**WHEREAS, SHELKO Electronics Co., Ltd.** a Korean corporation of **Rm. 1127, Hyundai Venture Vill, 713 Suseo-dong, Gangnam-gu, Seoul 135-539 Republic of Korea**

**ASSIGNEES**, are desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

**NOW, THEREFORE**, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said **ASSIGNOR(S)** have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said **ASSIGNEE**, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said **ASSIGNEE**, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

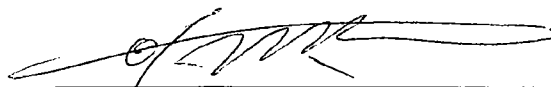
**AND I/WE HEREBY** covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

**AND I/WE HEREBY** further covenant and agree that I/we will communicate to said *ASSIGNEE*, its successors, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said *ASSIGNEE*, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the *ASSIGNEES*.

**IN TESTIMONY WHEREOF**, I/we hereunto set my/our hand(s) and seal(s) the day and year set opposite my/our signature(s).

10/06/10

Date



LEE, Jong Min

10/06/10

Date



PARK, Ju Gun

10/06/10

Date



OH, Jong Min

10/06/10

Date



OH, Jong Hyok

Witness:

NAM, Seon Yeon

Date

10/06/10

Name : NAM, Seon Yeon

Inventor Sole/Joint Assignment  
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